

# TOSOH SMD

### Sputter Sentry™

Process Monitor for Sputtering Targets

- Early warning for target erosion
- Detects sputter at the end of target life
- Closed loop compensation
- Real-time and historical data collection
- Remote data acquisition with wireless



### Copper Anodes

From 4N to 6N Purity

- High conductivity
- Excellent performance for sputter applications
- Available in bulk or plate form



### Extensive sputter Precursor for

MO-CVD

Ru



### THE GLOBAL LEADER

in TARGET



ISO 14001

### Colt-Sentry™

Double the Target Life with Superior Uniformity

Al



Ti



### Advanced PVD Materials for 300mm Wafers

Cu



Co



Ta



### Characterize Your CMP and Post-CMP Processes with Dimension Vx AFP



THE GLOBAL LEADER

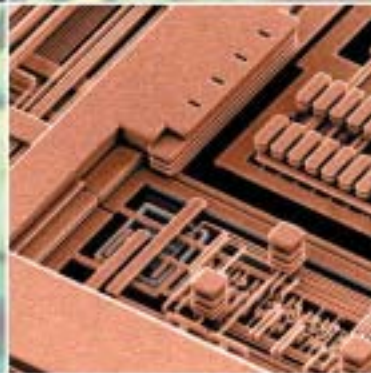
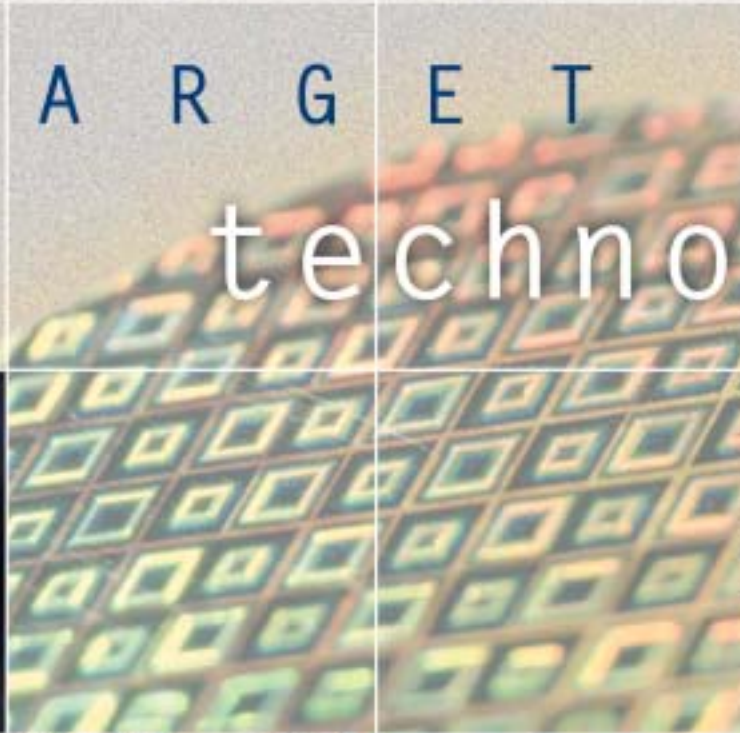
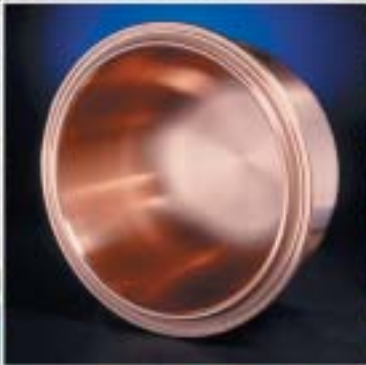
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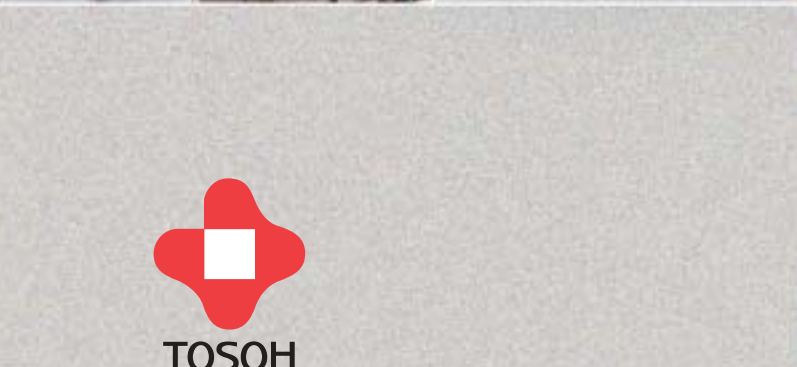


T A R G E T

technology™



ISO 9001



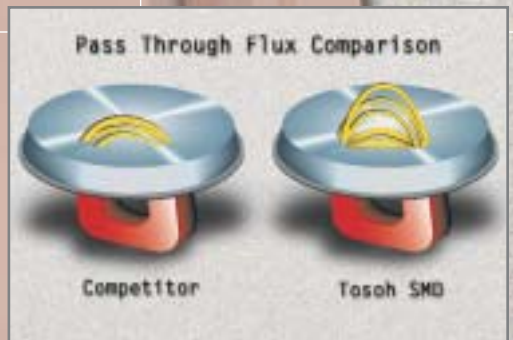
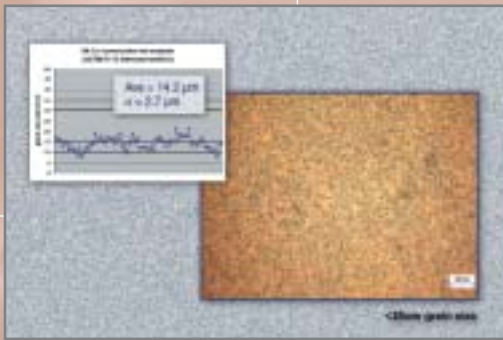
ISO 14001



# Advanced PVD Materials

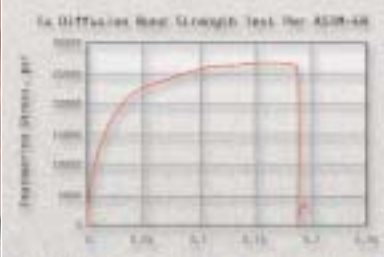
## for 300mm Wafers

Cu



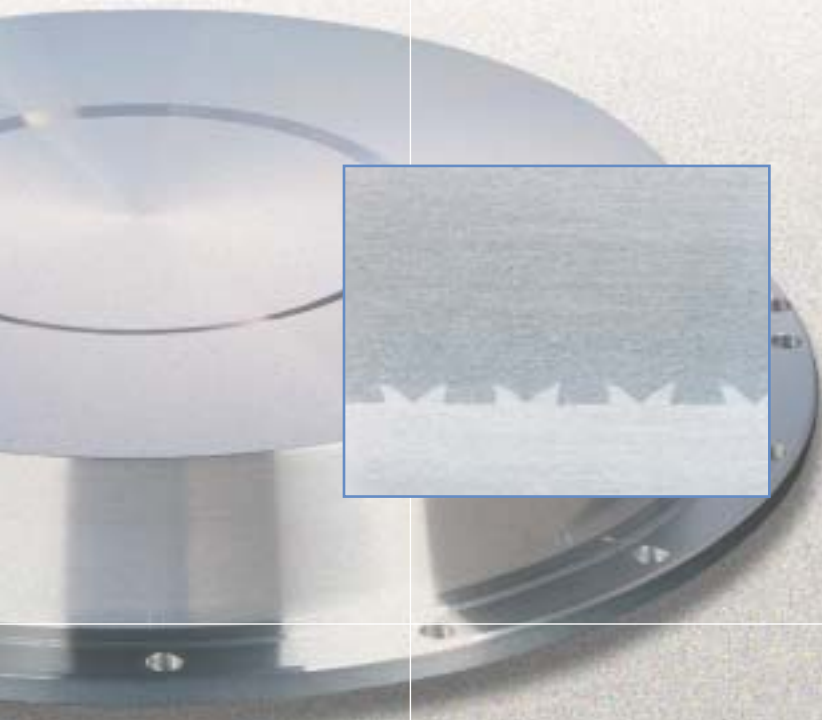
Co

Ta

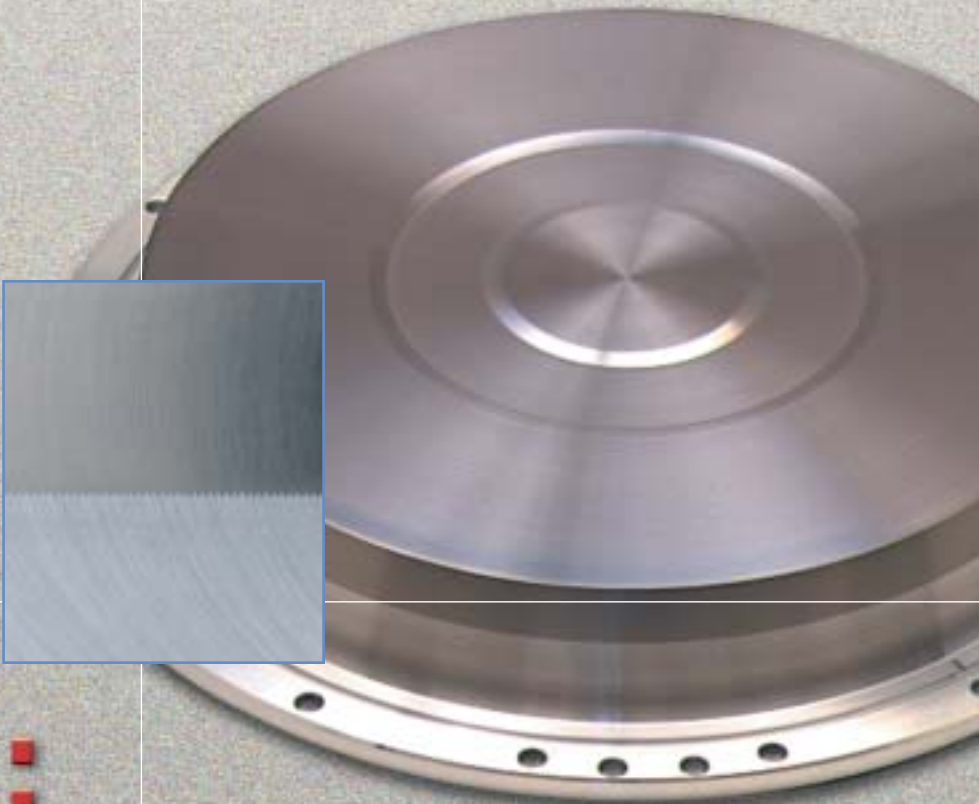


Solo Xtreme™

Double the Target Life  
with Superior Uniformity



Ti

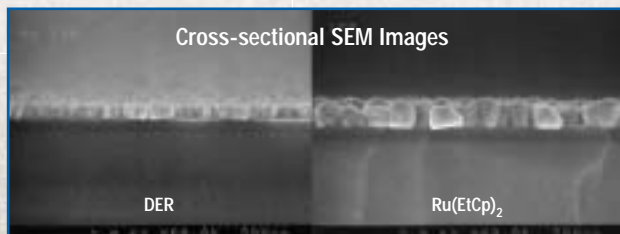


Ti



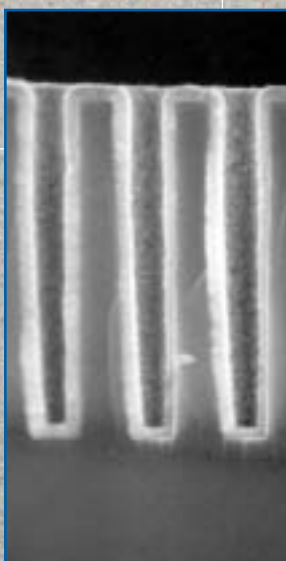
# Ruthenium DER

## Precursor for MO - CVD



- High vapor pressure and excellent thermal stability
- Eliminates need for Ru seed layer when deposited on SiO<sub>2</sub> substrate
- Smoother surface morphology and highly oriented Ru films
- Higher nucleation density than Ru(EtCp)<sub>2</sub>

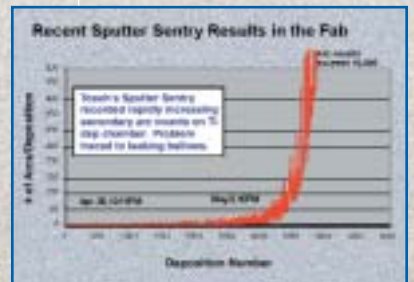
Ru



# Sputter Sentry™

## Process Monitor for Sputtering Targets

- Early warning for target arcing
- Sends alarm at the end of target life
- Clean room compatible
- Real-time and historical data evaluation
- Remote data acquisition and analysis



## Copper Anodes

from  
4N to 6N Purity

- High conductivity
- Better resistance to electromigration
- Available in pure or phosphorized form
- Consistent, fine grain microstructure

